



Material Content Data Sheet



Sales Product Name				BTS50080-1TMB		Issued		14. September 2018	
MA#				MA001044088					
Package				PG-TO220-7-12		Weight*		2119.00 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	5.233	0.25	0.25	2470	2470	
chip_2	inorganic material	silicon	7440-21-3	1.157	0.05	0.05	546	546	
leadframe	inorganic material	phosphorus	7723-14-0	0.272	0.01		129		
	non noble metal	iron	7439-89-6	0.908	0.04		428		
	non noble metal	copper	7440-50-8	906.793	42.80	42.85	427932	428489	
	non noble metal	aluminium	7429-90-5	2.541	0.12	0.12	1199	1199	
wire	organic material	carbon black	1333-86-4	8.868	0.42		4185		
	plastics	epoxy resin	-	97.546	4.60		46034		
encapsulation	inorganic material	silicondioxide	60676-86-0	484.776	22.88	27.90	228776	278995	
	non noble metal	tin	7440-31-5	23.005	1.09	1.09	10857	10857	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	102	103	
solder	non noble metal	tin	7440-31-5	0.079	0.00		37		
	noble metal	silver	7440-22-4	0.099	0.00		47		
	non noble metal	lead	7439-92-1	3.783	0.18	0.18	1785	1869	
	plastics	Polyimide	26023-21-2	0.143	0.01	0.01	67	67	
glue	inorganic material	phosphorus	7723-14-0	0.175	0.01		83		
heatspreader	non noble metal	iron	7439-89-6	0.584	0.03		275		
	non noble metal	copper	7440-50-8	582.824	27.50	27.54	275047	275405	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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